

**IN THE CLAIMS**

Please amend the claims as follows:

Claim 1 (currently amended): A ceramic heater to be used in semiconductor industry, comprising:

a disc-form ceramic substrate having a heating surface and comprising a nitride ceramic or a carbide ceramic;[[,]]

a resistance heating element comprising at least one circuit ~~or more circuits~~, said resistance heating element being arranged on a surface of said ceramic substrate;[[,]] and

an insulating covering deposited on the resistance heating element,

wherein said resistance heating element is positioned on an opposite side of said heating surface.

Claim 2 (previously presented): The ceramic heater to be used in semiconductor industry according to claim 1,

wherein said insulating covering is deposited in a stretch containing a portion where said circuit is formed.

Claim 3 (currently amended): The ceramic heater to be used in semiconductor industry according to claim 1,

wherein said ~~ceramic substrate comprises a nitride ceramic or a carbide ceramic~~ insulating covering comprises oxide glass.

Claim 4 (currently amended): The ceramic heater to be used in semiconductor industry according to claim 1,

wherein said insulating covering comprises ~~oxide glass~~ a heat resistant resin material.

Claim 5 (currently amended): The ceramic heater to be used in semiconductor industry according to claim ~~[[1]]~~ 4,

wherein said ~~insulating covering comprises a heat resistant resin material~~ heat resistant resin material is at least one resin material selected from the group consisting of a polyimide resin and a silicone resin.

Claim 6 (currently amended): The ceramic heater to be used in semiconductor industry according to claim [[5]] 1, wherein said ~~heat resistant resin material is one or more selected from a polyimide resin and a silicone resin~~ insulating covering covers the resistance heating element comprising two or more circuits in a lump.

Claim 7 (currently amended): The ceramic heater to be used in semiconductor industry according to claim 1, wherein ~~the opposite side to the side where said resistance heating element is formed is a heating surface~~ said insulating covering comprises oxide glass with a thickness of 5 to 20  $\mu\text{m}$ .

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Claim 8 (currently amended): The ceramic heater to be used in semiconductor industry according to claim 1, wherein said insulating covering ~~covers the resistance heating element comprising two or more circuits in a lump~~ comprises a heat resistant resin material with a thickness of 10 to 30  $\mu\text{m}$ .

Claim 9 (currently amended): The ceramic heater to be used in semiconductor industry according to claim 2, wherein said ~~ceramic substrate comprises a nitride ceramic or a carbide ceramic~~ insulating covering comprises oxide glass.

Claim 10 (currently amended): The ceramic heater to be used in semiconductor industry according to claim 2, wherein said insulating covering comprises ~~oxide glass~~ a heat resistant resin material.

Claim 11 (currently amended): The ceramic heater to be used in semiconductor industry according to claim [[3]] 2, wherein said insulating covering comprises oxide glass with a thickness of 5 to 20  $\mu\text{m}$ .

Claim 12 (currently amended): The ceramic heater to be used in semiconductor industry according to claim 2, wherein said insulating covering comprises a heat resistant resin material with a thickness of 10 to 30  $\mu\text{m}$ .

Claim 13 (currently amended): The ceramic heater to be used in semiconductor industry according to claim ~~[[3]]~~ 10, wherein said ~~insulating covering comprises a heat resistant resin material~~ heat resistant resin material is at least one resin material selected from the group consisting of a polyimide resin and a silicone resin.

DI Claim 14 (currently amended): The ceramic heater to be used in semiconductor industry according to claim 2, wherein ~~the opposite side to the side where said resistance heating element is formed is a heating surface~~ said insulating covering covers the resistance heating element comprising two or more circuits in a lump.

Claim 15 (currently amended): The ceramic heater to be used in semiconductor industry according to claim 3, wherein ~~the opposite side to the side where said resistance heating element is formed is a heating surface~~ said insulting covering covers the resistance heating element comprising two or more circuits in a lump.

Claim 16 (currently amended): The ceramic heater to be used in semiconductor industry according to claim 4, wherein ~~the opposite side to the side where said resistance heating element is formed is a heating surface~~ said insulating covering covers the resistance heating element comprising two or more circuits in a lump.

Claim 17 (currently amended): The ceramic heater to be used in semiconductor industry according to claim 5, wherein ~~the opposite side to the side where said resistance heating element is formed is a heating surface~~ said insulating covering covers the resistance heating element comprising two or more circuits in a lump.

Claim 18 (currently amended): The ceramic heater to be used in semiconductor industry according to claim [[6]] 1, ~~wherein the opposite side to the side where said resistance heating element is formed is a heating surface~~ further comprising a thermocouple.

Claim 19 (currently amended): The ceramic heater to be used in semiconductor industry according to claim [[2]] 18, wherein:

~~said insulating covering covers the resistance heating element comprising two or more circuits in a lump~~ ceramic substrate defines at least one through hole; and

said ceramic heater further comprises a lifter pin inserted through said through hole, said lifter pin being configured to support a semiconductor wafer at a distance above said ceramic substrate.

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Claim 20 (currently amended): The ceramic heater to be used in semiconductor industry according to claim [[3]] 18, ~~wherein said insulating covering covers the resistance heating element comprising two or more circuits in a lump~~ further comprising at least one bottom hole in a bottom surface of said ceramic substrate.

Claim 21 (currently amended): The ceramic heater to be used in semiconductor industry according to claim [[4]] 1,

~~wherein said insulating covering covers the resistance heating element comprising two or more circuits in a lump~~ resistance heating element is a metal or a conductive ceramic.

Claim 22 (currently amended): The ceramic heater to be used in semiconductor industry according to claim [[5]] 1,

~~wherein said insulating covering covers the resistance heating element comprising two or more circuits in a lump~~ resistance heating element is a sintered body produced from metal particles or conductive ceramic particles.

Claim 23 (canceled)

Claim 24 (previously presented): The ceramic heater to be used in semiconductor industry according to claim 7, wherein said insulating covering covers the resistance heating element comprising two or more circuits in a lump.

Claims 25-29 (canceled)